

AMENDMENTS TO THE CLAIMS:

Claims 1-14 (cancelled)

15. (New) A circuit substrate to be used for packaging a semiconductor device, comprising:

a main body having input/output terminal electrodes on a surface thereof, with each of said input/output terminal electrodes having

(i) a first surface that opposes said surface of said main body, and

(ii) a second surface that faces in a direction opposite to that in which said first surface faces;

conductive adhesive portions on said input/output terminal electrodes, with each of said conductive adhesive portions having

(i) a first surface that opposes said second surface of a respective one of said input/output terminal electrodes, and

(ii) a second surface that faces in a direction opposite to that in which said first surface faces; and

a resin film on said surface of said main body and covering said input/output terminal electrodes along with said conductive adhesive portions such that said resin film covers said first and second surfaces of said input/output terminal electrodes and also covers said first and second surfaces of said conductive adhesive portions.

16. (New) The circuit substrate according to claim 15, wherein said resin film contacts said second surface of said conductive adhesive portions.

17. (New) The circuit substrate according to claim 16, wherein said resin film contacts said second surface of said input/output terminal electrodes.

18. (New) The circuit substrate according to claim 15, wherein
each of said input/output terminal electrodes has a top side, a bottom side, and a lateral side
interconnecting said top and bottom sides,
each of said conductive adhesive portions has a top side, a bottom side, and a lateral side
interconnecting said top and bottom sides,
said resin film completely covers each of said input/output terminal electrodes on two of said
top side, said bottom side and said lateral side thereof, and
said resin film completely covers each of said conductive adhesive portions on two of said top
side, said bottom side and said lateral side thereof.

19. (New) A circuit substrate to have mounted thereon a semiconductor device,
comprising:
a main body having input/output terminal electrodes on a surface thereof;
a resin film having on one surface thereof conductive adhesive portions, and having on an
opposite surface thereof an elastomer layer,
wherein said elastomer layer is positioned on said opposite surface so as to correspond with
at least part of a surface of a semiconductor device on which a functional part of the semiconductor
device resides, when the semiconductor device is mounted on the circuit substrate, and
wherein said conductive adhesive portions are positioned on said one surface so as to
correspond with said input/output terminal electrodes.

20. (New) The circuit substrate according to claim 19, wherein
said resin film, with said conductive adhesive portions on said one surface thereof and with
said elastomer layer on said opposite surface thereof, is initially separate from said main body and is
then attached to said main body.

21. (New) The circuit substrate according to claim 20, wherein
said elastomer layer is softer and more elastic than said resin film.

22. (New) The circuit substrate according to claim 19, wherein said elastomer layer is softer and more elastic than said resin film.
23. (New) A package structure comprising:
a circuit substrate having input/output terminal electrodes, and conductive adhesive on each of said input/output terminal electrodes;
a semiconductor device having bump electrodes that are electrically and mechanically connected to said conductive adhesive and to said input/output terminal electrodes, said bump electrodes being in contact with said input/output terminal electrodes; and
resin between said circuit substrate and said semiconductor device, said resin bonding and fixing said semiconductor device to said circuit substrate.
24. (New) The package structure according to claim 23, further comprising:
an elastomer layer interposed between said resin and a functional part of said semiconductor device, said elastomer layer being softer and more elastic than said resin.
25. (New) The package structure according to claim 24, wherein said resin comprises a resin film or a sealing resin.
26. (New) The package structure according to claim 25, wherein said bump electrodes pass through said resin film or sealing resin.
27. (New) The package structure according to claim 24, wherein said bump electrodes pass through said resin film or sealing resin.
28. (New) The package structure according to claim 23, wherein said resin comprises a resin film or a sealing resin.

29. (New) The package structure according to claim 28, wherein said bump electrodes pass through said resin film or sealing resin.

30. (New) The package structure according to claim 23, wherein said bump electrodes pass through said resin.